



## PATENT ABSTRACTS OF JAPAN

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(71) Applicant: FURUKAWA ELECTRIC CO  
LTD:THE(72) Inventor: YAMAMOTO MASAOKI  
YAMAMORI KAZUYUKI  
HAMADA HIROKI  
KOBAYASHI KENZO(54) HIGH-DENSITY HEAT RADIATION TYPE  
CIRCUIT BOARD

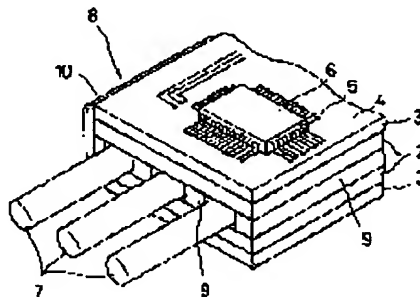
## (57) Abstract:

**PURPOSE:** To increase the mounting area of a heat radiation type circuit board where heating components such as a semiconductor element, etc., are mounted, and cope easily with specification change, and besides, facilitate the maintenance.

**CONSTITUTION:** This is a high-density heat radiation type circuit board where a plurality of sheets of heat radiation type circuit boards being made by uniting printed circuit boards 3 with heat sinks 2 are combined up and down so that the printed circuit board faces may surface and heat pipes 7 are arranged

through a spacer 9 at the heat sinks on the inside, and also the printed circuit boards are coupled with each other by a coupling 10.

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